

IN THE CLAIMS:

Claim 1 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

preparing an upper substrate and a lower substrate;

bonding the upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates to remove foreign materials formed ~~thereon~~ on the lower substrate during said steps the preparing of the lower substrate; and

simultaneously eliminating the cleaned exposed surfaces of the bonded upper and lower substrates.

Claim 2 (Original): The method according to claim 1, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 3 (Original): The method according to claim 1, wherein the step of eliminating the exposed surfaces includes wet-etching.

Claim 4 (Original): The method according to claim 1, further including the steps of:

- forming a thin film transistor on the lower substrate;
- forming a protective layer on the lower substrate; and
- forming a pixel electrode on the protective layer to electrically contact the thin film transistor.

Claim 5 (Previously Presented): The method according to claim 4, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 6 (Previously Presented): The method according to claim 4, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, fluorinated polymer, benzocyclobutene (BCB), and perfluorocyclobutane (PFCB).

Claim 7 (Original): The method according to claim 4, wherein the step of forming the thin film transistor includes:

- forming a gate electrode on the lower substrate;
- forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and
forming a source electrode and a drain electrode on the active layer.

Claim 8 (Original): The method according to claim 7, wherein the source electrode and drain electrode contact the gate insulating film.

Claim 9 (Previously Presented): The method according to claim 7, wherein the pixel electrode contacts flat and inclined surfaces of the drain electrode via a contact hole to expose the drain electrode.

Claim 10 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

bonding an upper substrate to a lower substrate;
cleaning exposed surfaces of the bonded upper and lower substrates to remove foreign materials formed thereon on the lower substrate during said steps preparation of the lower substrate; and
simultaneously removing the cleaned exposed surfaces of the bonded upper and lower substrates.

Claim 11 (Original): The method according to claim 10, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 12 (Original): The method according to claim 10, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 13 (Original): The method according to claim 10, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 14 (Currently Amended): A method of fabricating a liquid crystal display panel, comprising the steps of:

forming a gate electrode on a lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and

forming a source electrode and a drain electrode on the active layer;

forming a protective layer on the lower substrate;

bonding an upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates to remove foreign materials formed ~~thereon~~ on the lower substrate during said steps the forming of the protective layer; and

simultaneously removing the cleaned exposed surfaces of the bonded upper and lower substrates.

Claim 15 (Original): The method according to claim 14, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 16 (Original): The method according to claim 14, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 17 (Currently Amended): The method according to claim 14, further including the steps ~~step of forming a protective layer on the lower substrate;~~ and forming a pixel electrode on the protective layer to electrically contact the drain electrode.

Claim 18 (Previously Presented): The method according to claim 17, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 19 (Currently Amended): The method according to claim 17 14, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, fluorinated polymer, benzocyclobutene (BCB), and perfluorocyclobutane (PFCB).

Claim 20 (Previously Presented): The method according to claim 14, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 21 (Previously Presented): The method according to claim 1, wherein the step of simultaneously eliminating the exposed surfaces of the bonded upper and lower substrates uniformly reduces a thickness of the liquid crystal display panel.